

## **FEATURES**

- | 3600Watts peak pulse power (tp =  $8/20\mu$ s)
- | Solid-state silicon-avalanche technology
- Working voltages: 7V
- Low clamping voltage
- Low leakage current

## **APPLICATIONS**

- Power lines
- Personal digital assistants (PDA's)
- | Microprocessors based equipment
- Notebooks, Desktops, and Servers
- Cell phone Handsets and Accessories
- Portable Electronics
- Peripherals





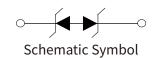
## **IEC COMPATIBILITY**

| IEC61000-4-2 (ESD)  $\pm$ 30kV (air),  $\pm$ 30kV (contact)

| IEC61000-4-4 (EFT) 40A (5/50ns)

## **APPROVALS**

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003



## THERMAL CONSIDERATIONS

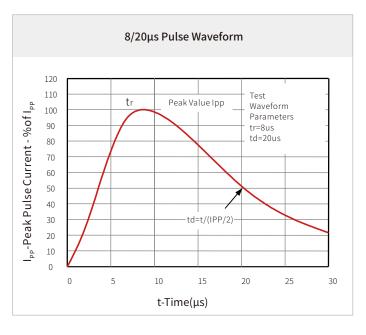
Symbol	Parameter	Value	Unit
$P_{pp}$	Peak Pulse Power (tp=8/20µs waveform)	3600	Watts
T <sub>J</sub>	T <sub>J</sub> Operating Temperature Range -5.		°C
T <sub>stg</sub>	Storage Temperature Range	-55 to +150	°C

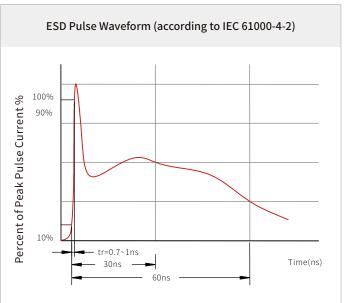
# **ELECTRICAL CHARACTERISTICS**

Symbol	Parameter	Condition	Min.	Тур.	Max.	Unit
$V_{RWM}$	Reverse Stand-offVoltage				7.0	V
$V_{BR}$	Reverse Breakdown Voltage	I <sub>⊤</sub> =1mA	7.78			V
I <sub>R</sub>	Reverse Leakage Current	V <sub>RWM</sub> =7V			1	μΑ
V <sub>c</sub>	Clamping Voltage	I <sub>PP</sub> =200A,tp=8/20μs			18	V
I <sub>PP</sub>	Peak Pulse Current	tp=8/20μs			200	А
C	Off State Junction Capacitance	V <sub>R</sub> =0V, f=1MHz		1220		pF



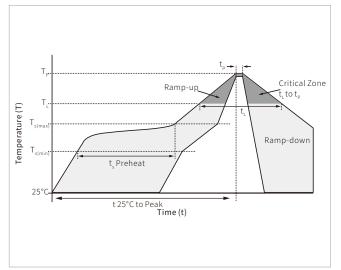
# **CHARACTERISTIC CURVES**





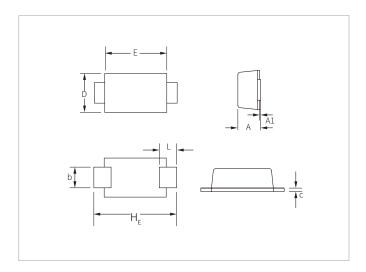
# **SOLDERING PARAMETERS**

	Lead-free assembly		
	Temperature Max (T <sub>s(min)</sub> )	150°C	
Pre Heat	Temperature Max (T <sub>s(max)</sub> )	200°C	
	Time (min to max) $(t_s)$	60 – 180 secs	
Average ran	Average ramp up rate (Liquidus Temp (T <sub>L</sub> ) to peak		
	T <sub>s(max)</sub> to T <sub>L</sub> - Ramp-up Rate		
Reflow	Temperature (T <sub>L</sub> ) (Liquidus)	217°C	
Kellow	Time (min to max) $(t_L)$	60 – 150 seconds	
Peak Temp	260°C		
Time within	20 – 40 seconds		
Ramp-dow	6°C/second max		
Time 25°C t	8 minutes max.		
Do not exce	260°C		



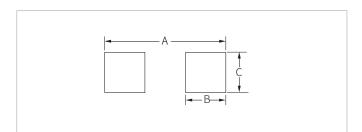


# **SOD-123FL PACKAGE INFORMATION**



Ref.	Millimeters		Inches	
Kei.	Min.	Max.	Min.	Max.
А	0.95	1.45	0.037	0.057
A1	0.00	0.10	0.000	0.004
b	0.70	1.20	0.028	0.047
С	0.05	0.30	0.002	0.012
D	1.50	2.00	0.059	0.079
E	2.50	3.10	0.098	0.122
L	0.35	0.90	0.014	0.035
H <sub>E</sub>	3.40	3.90	0.134	0.154

# **RECOMMENDED PAD LAYOUT DIMENSIONS**



Ref.	Millimeters	Inches
А	4.20	0.165
В	1.50	0.059
С	1.20	0.047

# **ORDERING INFORMATION**

Part Number	Component Package	QTY/Reel	Reel Size
SE1D360B7.0A	SOD-123FL	3000PCS	7"



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### By QR Code





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